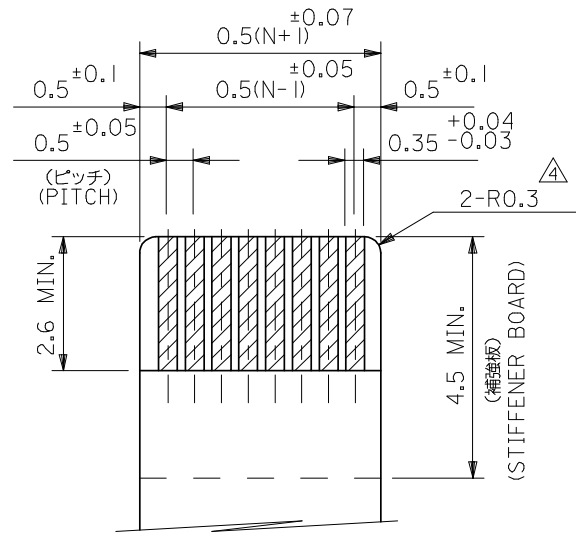
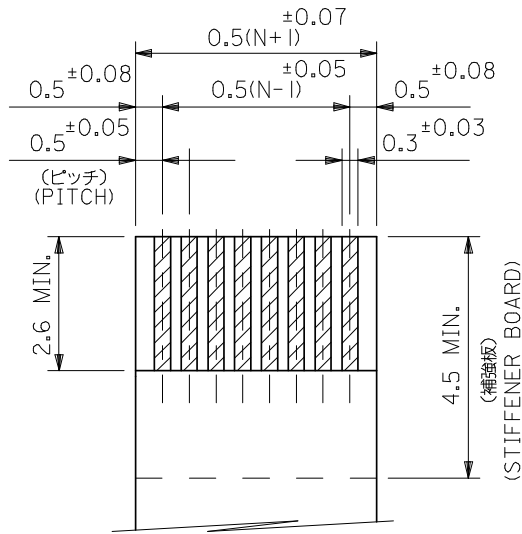


13.5	12.5	15.1	51281-2694	51281-2640	26
12.5	11.5	14.1	51281-2494	51281-2440	24
11.5	10.5	13.1	51281-2294	51281-2240	22
10.5	9.5	12.1	51281-2094	51281-2040	20
9.5	8.5	11.1	51281-1894	51281-1840	18
8.5	7.5	10.1	51281-1694	51281-1640	16
7.5	6.5	9.1	51281-1494	51281-1440	14
6.5	5.5	8.1	51281-1294	51281-1240	12
5.5	4.5	7.1	51281-1094	51281-1040	10
5.0	4.0	6.6	51281-0994	51281-0940	9
4.5	3.5	6.1	51281-0894	51281-0840	8
3.5	2.5	5.1	51281-0694	51281-0640	6
3.0	2.0	4.6	51281-0594	51281-0540	5
C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	CIRCUIT

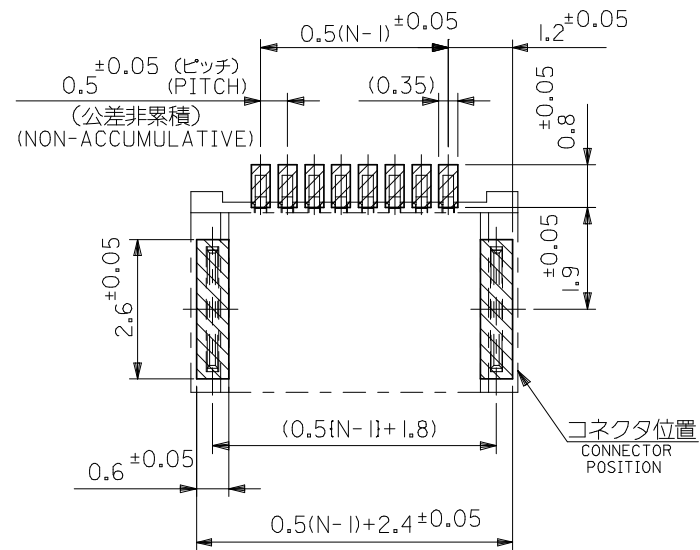
REVISED EC NO: J2008-4308 DRWN:MNABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KENSUZUKI	DATE 2004/10/19	TITLE 0.5 FPC CONN NON-ZIF HSG ASSY (HGT=1.2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY NUKITA	DATE 2004/10/19	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2004/10/19	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-51281-011	SHEET NO. 1 OF 2
	ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ±0.03)
(THICKNESS: 0.3 ±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ±0.03)
(THICKNESS: 0.3 ±0.03)



参考基板レイアウト図
RECOMMENDED P.C. BOARD LAYOUT
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填 UL94V-0
HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0
ターミナル : リン青銅 (t=0.2), ニッケル下地 コンタクト部: 金メッキ
TERMINAL : PHOSPHOR-BRONZE, CONTACT : GOLD テール部: 錫メッキ
TAIL : TIN
OVER NICKEL PLATING
金具 : リン青銅 (t=0.25), ニッケル下地 純錫メッキ
FITTING NAIL : PHOSPHOR-BRONZE, PURE-TIN OVER NICKEL PLATING.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 J に対し、上方向 0.1 MAXIMUM 下方向 0.15 MAXIMUM とする。
又、相互のバラツキ量は 0.1 MAXIMUM とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM J
UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.
OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.
- △ 偶数極に適用。
TO BE APPLIED ONLY WHEN ALL CIRCUIT ARE EVEN.
- △ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

5. FPC/FFCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35μmまたは50μm
メッキ厚 0.1μm 金メッキ (電気メッキ)
を推奨いたします。
RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 μm or 50 μm
GOLD PLATING : 0.1 μm (ELECTRICAL PLATING)
6. 本製品は51281-**-20の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 51281-**-20.
7. ソルダータールの平坦度は、0.1 MAXIMUM とする。
SOLDER TAIL COPLANARITY IS 0.1 MAXIMUM.

REVISED EC NO: J2008-4308 DRWN: WABEI 2008/06/27 CHKD: THARUYAMA 2008/06/30 APPR: NUKITA 2008/06/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	51281-**-40	MODEL NO.	
				MM ONLY		---	DESIGN UNITS	THIRD ANGLE PROJECTION	
						TITLE			
						0.5 FPC CONN NON-ZIF HSG ASSY (HGT=1.2MM) -LEAD FREE-			
REV G	REV	10 UNDER	±0.2	DRAWN BY	DATE	MOLEX	MOLEX INCORPORATED		
		10 OVER 30 UNDER	±0.25	CHECKED BY	DATE		DOCUMENT NO.		SHEET NO.
		30 OVER	±0.3	APPROVED BY	DATE		SD-51281-011		2 OF 2
		ANGULAR	±3 °	MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1					
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							